厚板高縱橫比直流電鍍銅技術

DC Copper Plating for Thick Panel

ELECTROPOSIT™ 1500 Acid Copper

The latest technology, ELECTROPOSIT™ 1500 Acid Copper, is developed by Dow Electronic Materials for thick panel plating which provides excellent throwing power than conventional products.

ELECTROPOSIT™ 1500電鍍銅為陶氏化學電子材料所開發之最新一代應用於厚板之直流電鍍技術。相較於過往產品，它能提供絕佳的通孔深鍍能力。

Advantages 優點

- High throwing power on high aspect ratio boards
  於高縱橫比之厚板下具有高通孔深鍍能力之表現
- Microvia plating capability
  可同時兼顧盲孔電鍍
- Full Analysis System by CVS
  可使用CVS分析控管所有添加劑
- Excellent Thermal Reliability
  優異的熱信賴度

Table 1: High throwing power on high aspect ratio boards
於高縱橫比之厚板下，具有高通孔深鍍能力之表现

Board thickness (mm)	2.36		3.25	
Hole Diameter (mm)	0.15	0.2	0.20	0.25
Aspect Ratio	15.5:1	11.6:1	16.25:1	13:1
C.D. (ASF)	10	10	6	6
TP% and Knee TP%	>90%	>95%	>90%	>95%

Table 2: Excellent Thermal Reliability
優異的熱信賴度

Board thickness (mm)	3.25	3.25	2.36	2.36
Diameter (mm)	0.25	0.2	0.2	0.15
A/R	13:1	16.25:1	11.6:1	15.5:1
C.D. (ASF)	6	6	10	10
Reliability (Solder Float)	PASS	PASS	PASS	PASS

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